GaN HEMT 50V, 150W, 5.8GHz RF Power Transistor

Description

The STCV58150F4C is a single ended 150watt, GaN HEMT, ideal for ISM applications at 5.8GHz. It can support CW, pulse and linear applications.

There is no guarantee of performance when this part is used outside of stated frequencies.

- Typical pulse CW performance across the band with device soldered
- VDD = 50 Vdc,Idq=20mA Tc=25°C, air cooling

CW:

Freq	Psat	Psat	Psat	Power
(GHz)	(dBm)	(W)	Eff(%)	Gain(dB)
5.8	52.33	171	55	10.5

Recommended driver: STAV58030J2, and 5.7-5.9G data upon request

Applications

- C band Class AB power amplifier
- 5.8GHz RF Energy

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically –5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+200	Vdc
GateSource Voltage	V _{GS}	-8 to +0.5	Vdc
Operating Voltage	V _{DD}	55	Vdc
Maximum gate current	lgs	21	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	Rejc	0.95	°C /W
T_c = 25°C, at Pd=140W at 5.8GHz		0.85	

Table 3. Electrical Characteristics (TA = 25° C unless otherwise noted)

DC Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=21mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 21mA	V _{GS(th)}	-4	-	-2	V



Turning the device OFF

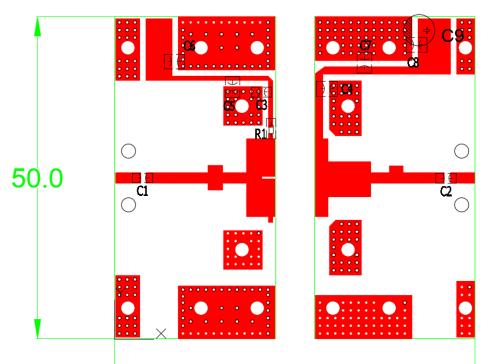
- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Document Number: STCV58150F4C Preliminary Datasheet V1.0

Gate Quiescent Voltage	VDS =50V, IDS=20mA, Measured in Functional Test	$V_{GS(Q)}$		3.1		V
Ruggedness Characteristics						
Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	5.8GHz, Pout=150W pulse CW					
	All phase, VSWR			10:1		
	No device damages					

Reference Circuit of Test Fixture Assembly Diagram

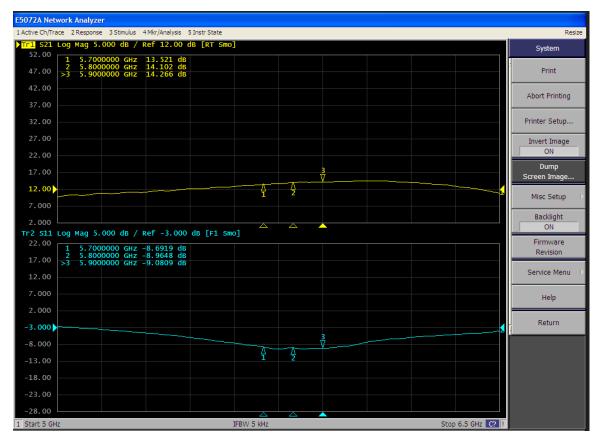
PCB materials: Ro4350B , DXF file upon request



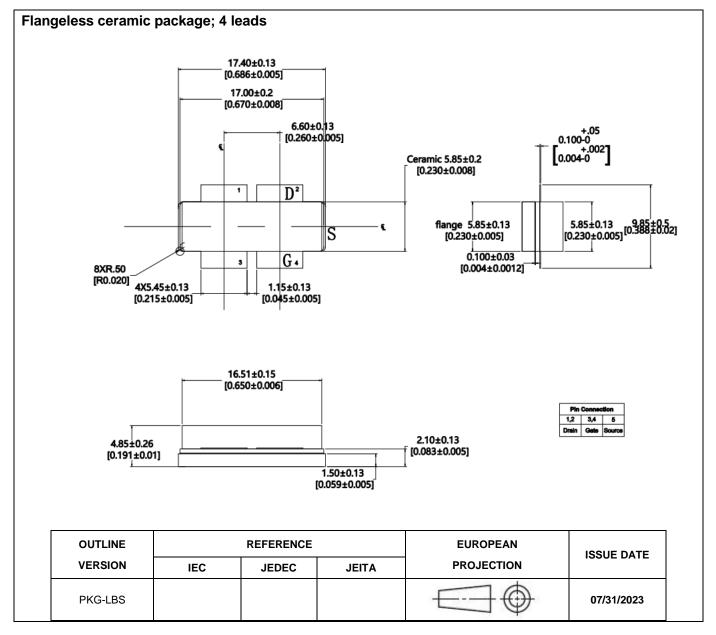
56.0

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Component	Description	Suggestion
C9	470uF/63V	
C5,C6,C7,C8	10uF	10uF/100V
01.00		BEIJING YUANLU HONGYUAN
C1, C3,	3.9pF(MQ300805)	ELECTRONIC TECHNOLOGY CO., LTD
00.04		BEIJING YUANLU HONGYUAN
C2 ,C4	3.9pF(MQ301111)	ELECTRONIC TECHNOLOGY CO., LTD
R1	Chip Resistor,10Ω	0805
РСВ	30mil Rogers 4350B	

Figure 4: S11/S21 output from Network analyser (VDS= 50V, IDQ=200 mA Vgs =-3.0V)



Package Outline



Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2024/10/12	V1.0	Preliminary Datasheet Creation

Application data based on: YHG-24-18

Notice

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